Docket No.: 2336-086



**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In an Application of	•
In re Application of	•

Jeong-Goo YOON et al.

Confirmation No. 9603

U.S. Patent Application No. 10/006,143

Group Art Unit: 2823

Filed: December 10, 2001

Examiner: G. Fourson III

For:

PROCESS FOR LAPPING WAFER AND METHOD FOR PROCESSING BACKSIDE OF WAFER

USING THE SAME

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

No additional fee is required.

Small entity status of this application has been established.

Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	7	20	0	x \$ 18 =	\$ 0.00
Independent Claims	3	3	0	x \$ 86 =	\$ 0.00
		If multiple claims newly presented, add \$290.00			n/a
Fee for extension of time			n/a		
TOTAL FEE DUE			\$ 0.00		

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The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. <u>07-1337</u>, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Kindly use the attorneys' address associated with the following Customer Number for future correspondence.

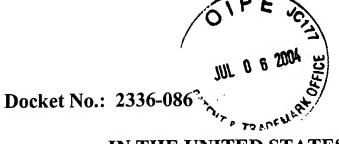
Respectfully submitted,

LOWETHAUPTMAN GILMAN & BERNER, LLP

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Date: July 6, 2004



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In re Application of

Jeong-Goo YOON et al. : Confirmation No. 9603

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For: PROCESS FOR LAPPING WAFER AND METHOD FOR PROCESSING BACKSIDE

OF WAFER USING THE SAME

## **AMENDMENT**

Commissioner for Patents P.O. Box 1450 Alexandria VA 22313-1450

Sir:

The following amendments and remarks are submitted in response to the Official Action dated *April 6, 2004*.